

200mW SOD-323 SURFACE MOUNT Small Outline Gull Wing Lead Plastic Package Fast Switching Diode

Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
PD	Power Dissipation	200	mW	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TJ	Operating Junction Temperature	+150	°C	
V _{RSM}	Non-Repetitive Peak Reverse Voltage	100	V	
V _{RRM}	Repetitive Peak Reverse Voltage	75	V	
I _{FRM}	Repetitive Peak Forward Current	300	mA	
lo	Continuous Forward Current	150	mA	
I _{FSM}	Peak Forward Surge Current (Pulse Width=1us)	2	А	

These ratings are limiting values above which the serviceability of the diode may be impaired.

Specification Features:

- Fast Switching Device (T_{RR} <4.0 nS)</p>
- General Purpose Diodes
- Gull Wing Lead SOD-323 Small Outline Plastic Package
- Surface Device Type Mounting
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode
- Weight: approx. 0.0046g

Electrical Characteristics T_A = 25°C unless otherwise noted

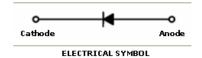
Symbol	Parameter		Test Condition	Limits		
				Min	Max	Unit
Bv	Breakdown Voltage		I _R =100μΑ	100		Valta
			Ι _R =5μΑ	75		Volts
I _R	Reverse Leakage Current		V _R =20V		25	nA
			V _R =75V		5	μA
VF	Forward Voltage	1N4448WSG	I _F =5mA	0.62	0.72	
		1N4148WSG	I _F =10mA		1.0	Volts
		1N4448WSG	I _F =100mA		1.0	
T _{RR}	Reverse Recovery Time		I _F =10mA			
			I _R =60mA			. 0
			R _L =100Ω		4	nS
			I _{RR} =1mA			
С	Capacitance		V _R =0V, f=1M _{HZ}		4	pF

Green Product

SEMICONDUCTOR



SOD-323 Gull Wing Lead

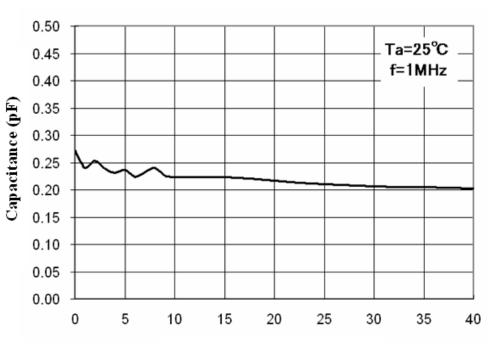


DEVICE MARKING CODE:

Device Type	Device Marking			
1N4148WSG	T4			
1N4448WSG	T5			

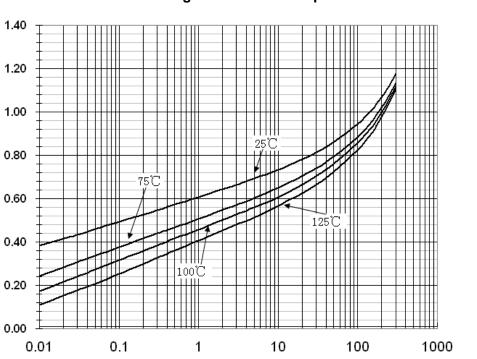


Typical Performance Characteristics



Total Capacitance

Reverse Voltage (V)

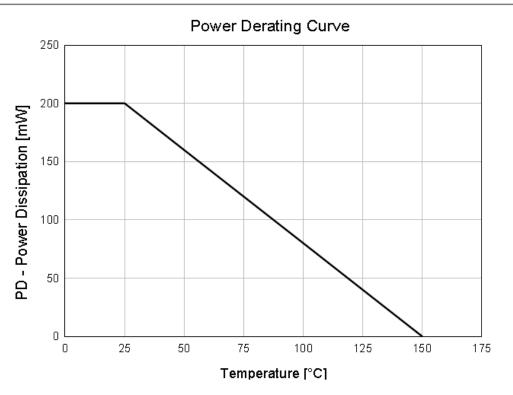


Forward Voltage vs Ambient Temperature

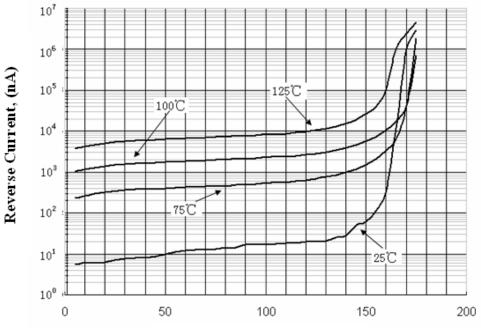
Number: DB-286 May 2017 Release, Revision A



SEMICONDUCTOR





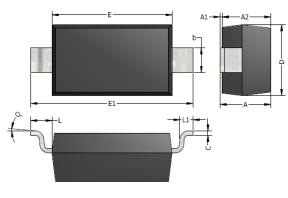


Reverse Voltage, VR (V)

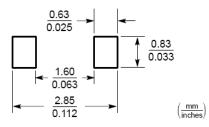


SEMICONDUCTOR

SOD-323 Gull Wing Lead Package Outline



Typical Soldering Pattern:



DIM	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
А	0.80	1.00	0.031	0.039	
A1	0.00	0.10	0.000	0.004	
A2	0.80	0.90	0.031	0.035	
b	0.30	0.40	0.012	0.016	
С	0.08	0.15	0.003	0.006	
D	1.20	1.40	0.047	0.055	
Е	1.60	1.80	0.063	0.071	
E1	2.50	2.70	0.098	0.106	
L	0.475 REF.		0.019 REF.		
L1	0.25	0.40	0.010	0.016	
θ	0 °	8 °	0 °	8 °	

Note: Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.



NOTICE

The information presented in this document is for reference only. Tak Cheong reserves the right to make changes without notice for the specification of the products displayed herein.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Tak Cheong Semiconductor Co., Ltd., or anyone on its behalf, assumes no responsibility or liability for any damagers resulting from such improper use of sale.

This publication supersedes & replaces all information reviously supplied. For additional information, please visit our website <u>http://www.takcheong.com</u>, or consult your nearest Tak Cheong's sales office for further assistance.